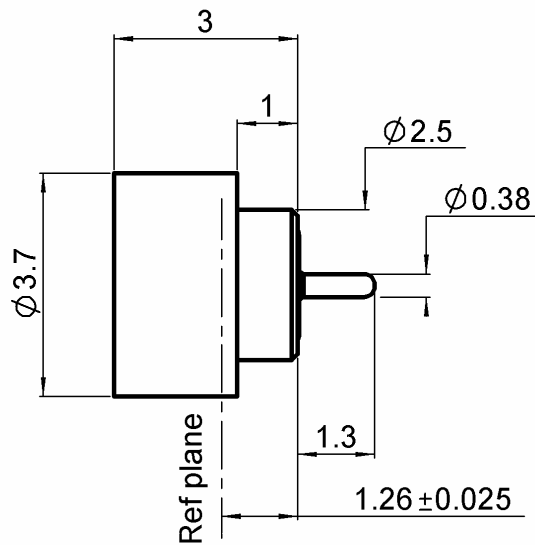


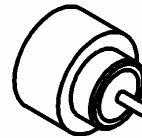
**HERMETIC STRAIGHT MALE RECEPTACLE**  
**SOLDER TYPE - SMOOTH BORE**

**R222.645.720**

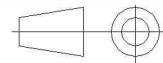
Series : SMP



Scale 1/1



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY	DILVER P1	GOLD 0.5 OVER NICKEL 2
CENTER CONTACT	DILVER P1	GOLD 0.5 OVER NICKEL 2
OUTER CONTACT		
INSULATOR	GLASS	
GASKET		
OTHERS PARTS		
-	-	-
-	-	-

Issue : 0951 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**HERMETIC STRAIGHT MALE RECEPTACLE****R222.645.720****SOLDER TYPE - SMOOTH BORE**

Series : SMP

**PACKAGING**

Standard	Unit	Other
<b>100</b>	<b>'W' option</b>	<b>Contact us</b>

**SPECIFICATION****ELECTRICAL CHARACTERISTICS**

Impedance	<b>50</b>	$\Omega$
Frequency	<b>0-18</b>	GHz
VSWR	<b>1.15 + 0,0000</b>	x F(GHz) Maxi
Insertion loss	<b>0.12</b>	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	- (	- F(GHz)) dB Maxi
Voltage rating	<b>335</b>	Veff Maxi
Dielectric withstanding voltage	<b>500</b>	Veff mini
Insulation resistance	<b>5000</b>	M $\Omega$ mini

**ENVIRONMENTAL**

Operating temperature	<b>-65/+165</b>	$^{\circ}\text{C}$
Hermetic seal	<b>10-8</b>	Atm.cm <sup>3</sup> /s
Panel leakage	<b>NA</b>	

**OTHERS CHARACTERISTICS**

Assembly instruction

Others :

**MECHANICAL CHARACTERISTICS**

Center contact retention	
Axial force – Mating end	<b>6.8</b> N mini
Axial force – Opposite end	<b>6.8</b> N mini
Torque	<b>NA</b> N.cm mini
Recommended torque	
Mating	<b>NA</b> N.cm
Panel nut	<b>NA</b> N.cm
Mating life	<b>1000</b> Cycles mini
Weight	<b>0,0850</b> g

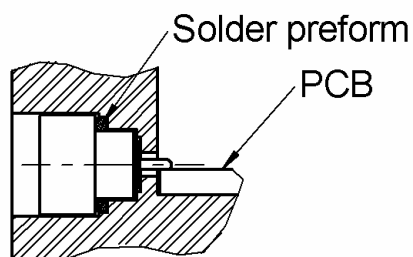
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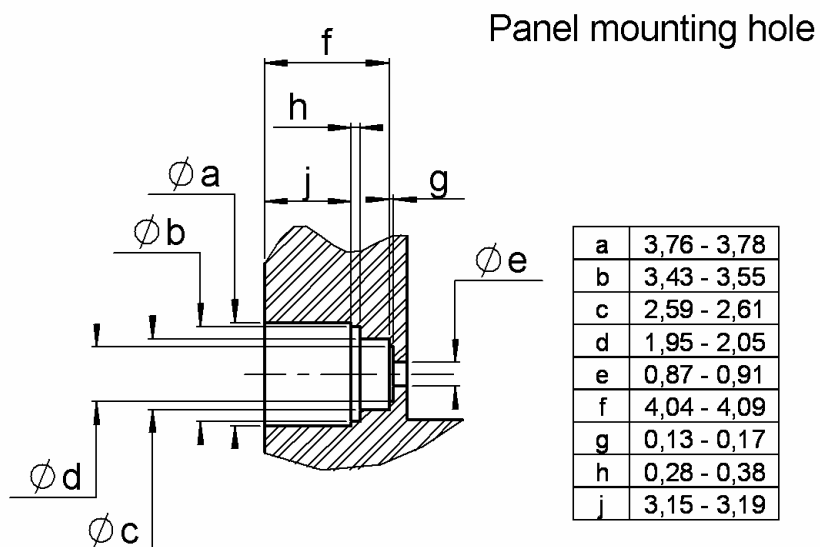


**HERMETIC STRAIGHT MALE RECEPTACLE****SOLDER TYPE - SMOOTH BORE****R222.645.720**

Series : SMP



1. Degrease and clean connector and box
2. Solder the connector on the panel  
we advise SnAg4 Cu0.5, we recommend a low residue flux.  
Preheating at 100 °C. Take care not to exceed 260°C during solder operation
3. Solder the pin on the track  
we advise SnAg4 Cu0.5, we recommend a low residue flux.  
Preheating at 100 °C (only for ceramic substrate). Take care not to exceed 260°C during solder operation

**Issue : 0951 B**

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

